
**UNITED STATES
SECURITIES AND EXCHANGE COMMISSION
Washington, DC 20549**

FORM 8-K

**CURRENT REPORT
Pursuant to Section 13 or 15(d) of the
Securities Exchange Act of 1934**

**Date of Report (Date of earliest event reported)
May 12, 2010**

AMKOR TECHNOLOGY, INC.

(Exact name of registrant as specified in its charter)

DELAWARE

(State or Other
Jurisdiction of
Incorporation)

000-29472

(Commission File Number)

23-1722724

(IRS Employer
Identification No.)

**1900 SOUTH PRICE ROAD
CHANDLER, AZ 85286**

(Address of Principal Executive Offices, including Zip Code)

(480) 821-5000

(Registrant's telephone number, including area code)

Check the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions:

- ☐ Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
 - ☐ Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
 - ☐ Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
 - ☐ Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c))
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Item 7.01. Regulation FD Disclosure.

On May 12, 2010, Amkor Technology, Inc. will be participating in the Credit Suisse Electronics Supply Chain & Semi-Cap Conference, held in Boston, MA. Attached hereto as Exhibit 99.1 and incorporated by reference herein, is a copy of the materials to be presented to investors at that conference. A copy of the investor presentation is available on the company's website: www.amkor.com.

The information in this Form 8-K and the exhibit attached hereto is being furnished and shall not be deemed "filed" for purposes of Section 18 of the Securities Exchange Act of 1934, as amended (the "Exchange Act") or otherwise subject to the liabilities of that section, nor shall it be deemed incorporated by reference in any filing under the Securities Act of 1933, as amended, or the Exchange Act, regardless of any general incorporation language in such filing.

Item 9.01. Financial Statements and Exhibits.

(d) Exhibits.

99.1 Investor Presentation dated May 2010, which is furnished (not filed) herewith.

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

AMKOR TECHNOLOGY, INC.

By: /s/ Gil C. Tily
Gil C. Tily
Executive Vice President, Chief Administrative Officer and
General Counsel

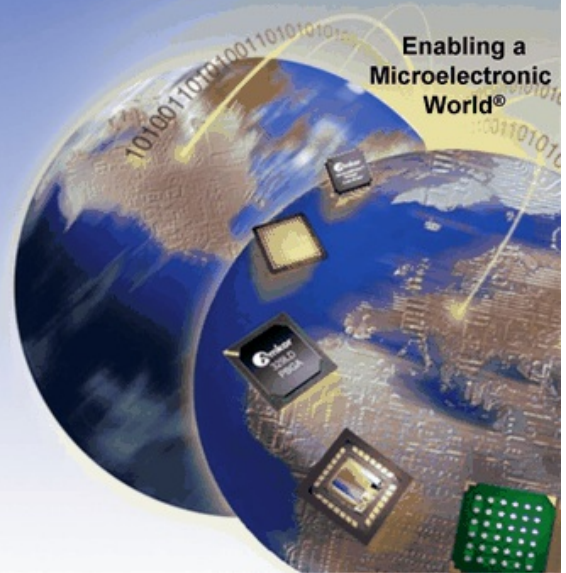
Date: May 12, 2010

EXHIBIT INDEX:

Exhibit	Description
99.1	Investor Presentation dated May 2010

Amkor Investor Presentation

May 2010



Forward Looking Statement Disclaimer

All information and other statements contained in this presentation, other than statements of historical fact, constitute forward looking statements within the meaning of federal securities laws. These forward-looking statements involve a number of risks, uncertainties, assumptions and other factors that could affect our future results and cause actual results and events to differ materially from our historical and expected results and those expressed or implied in these forward looking statements. Our historical financial information, and the risks and other important factors that could affect the outcome of the events set forth in these statements and that could affect our operating results and financial condition, are contained in our filings with the Securities and Exchange Commission, including our Form 10-K for the 2009 year and subsequent filings. We undertake no obligation to review or update any forward-looking statements to reflect events or circumstances occurring after this presentation.

Guidance Policy

Our financial guidance for the quarter is contained in our earnings release and is effective only on the date given. In accordance with our policy, we will not update, reaffirm or otherwise comment on any prior financial guidance in connection with this presentation.

- A global leader in the growing assembly and test industry
- Significant size and scale (\$2.4B revenues in LTM Q1'10)
- Industry innovator with broad offering of package design, packaging and test services
- Diversified global customer base in multiple electronics end markets
- Strategically positioned manufacturing operations
- Disciplined growth and focus on profitability
- Managing capital intensity with focus on free cash flow generation
- Sound balance sheet and liquidity



Outsourcing is Increasing in Importance



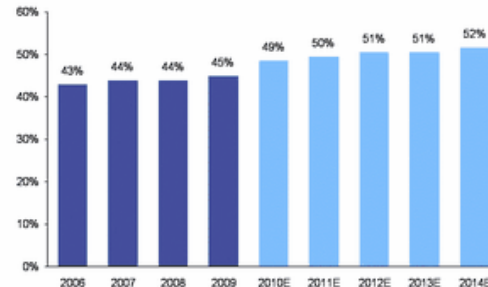
Amkor is a leading global outsourced assembly and test provider

Semiconductor Market Growth

Industry Analyst Semiconductor Forecasts 2010 vs. 2009

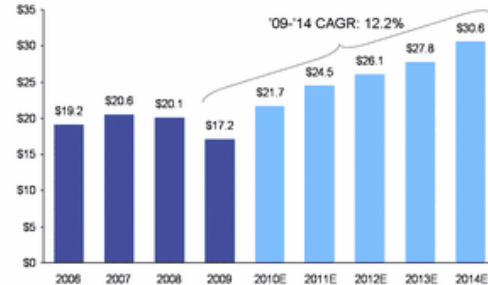
Industry Analyst	2010 Growth	Report Date
IC Insights	+28%	Apr. 2010
Semico Research	+24%	Feb. 2010
Future Horizons (MPenn)	+22%	Feb. 2010
Gartner/Dataquest	+20%	Feb. 2010
WSTS	+12%	Nov. 2009
SIA	+10%	Nov. 2009

Outsourced Backend Revenue as % of Total Backend Revenue



Total Outsourced Backend Revenue

(\$ in billions)



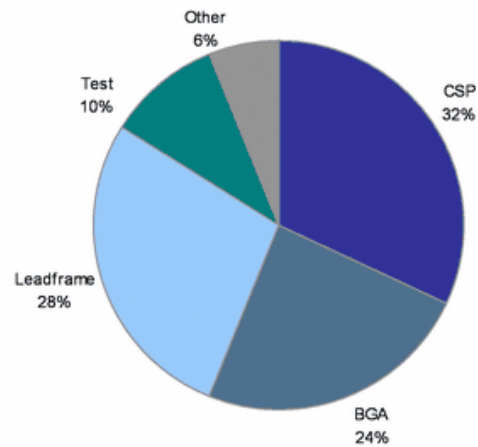
Source: Gartner, March 2010

Broad Offering of Packaging and Test Services



- Chip Scale Packaging ("CSP")
 - Small form factor greater I/O density
- Ball Grid Array Packaging ("BGA")
 - High performance and large number of interconnects
- Leadframe Packaging
 - Enhanced price and performance characteristics
- Probe and Test
 - Supporting advanced silicon solutions

Net Sales by Service Type

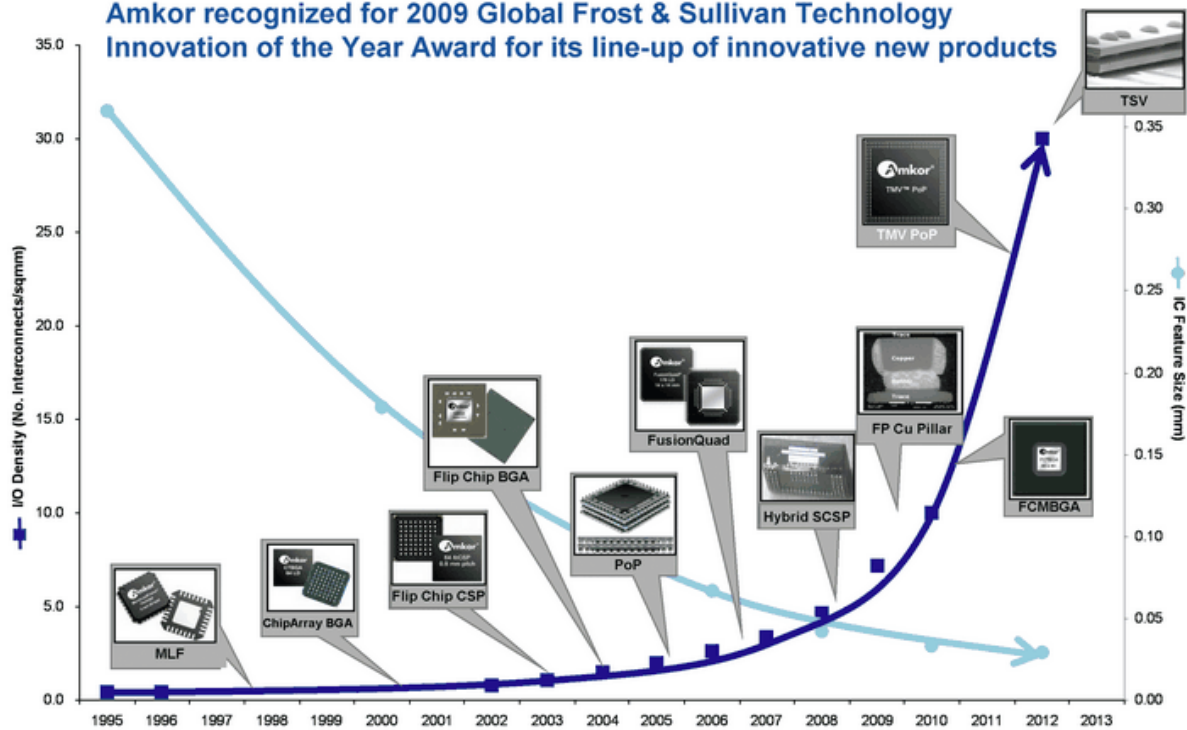


Based on Q1'10 Net Sales

Industry Innovator and Technology Leader



Amkor recognized for 2009 Global Frost & Sullivan Technology Innovation of the Year Award for its line-up of innovative new products



Moore's Law impact on packaging: IC feature size reductions drive smaller form factor and higher I/O density

Deep Ties to Tier-I Semiconductor Companies Serving Diverse Electronics End Markets



Communications

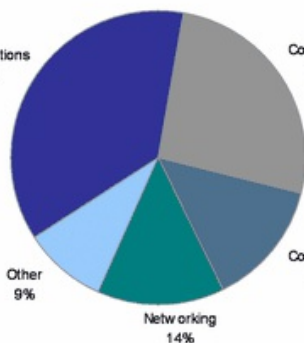
Handsets, Ethernet, WiMAX,
Wireless LAN and Bluetooth



Other



Communications
37%



Networking

Infrastructure, Routers and Networking
Servers



Consumer

Gaming, Set-Top Box, DTV, DVD, DSC,
Portable Media Players and Flash Memory Cards



Computing

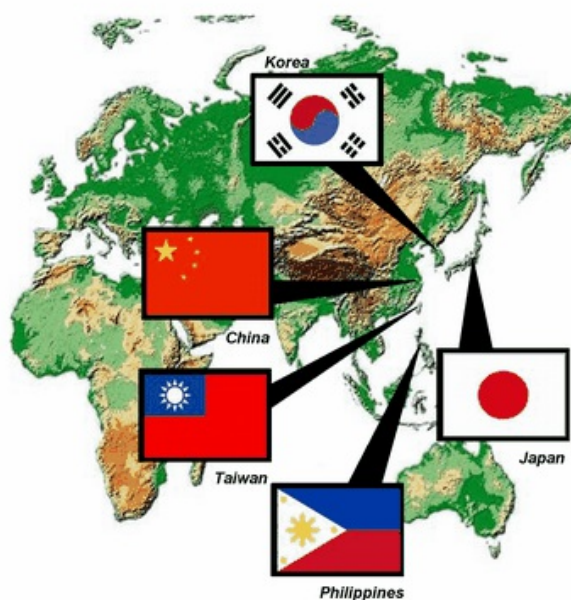
PCs, Computing Servers, Displays, HDD,
Printers and Multi-Function Peripherals



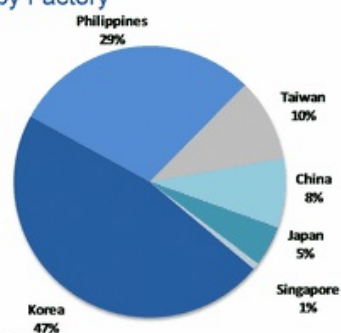
Revenue distribution based on Q1'10 Net Sales

Representative customers include:



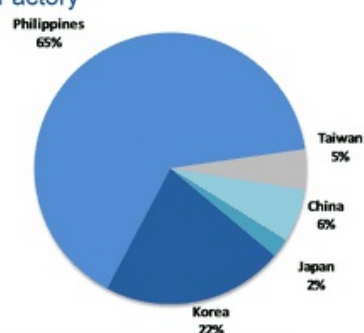


Net Sales by Factory



Based on Q1'10 Net Sales

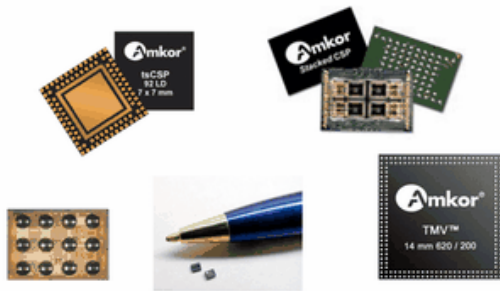
Units by Factory



Based on Q1'10 units shipped excluding wafer bumping and test services

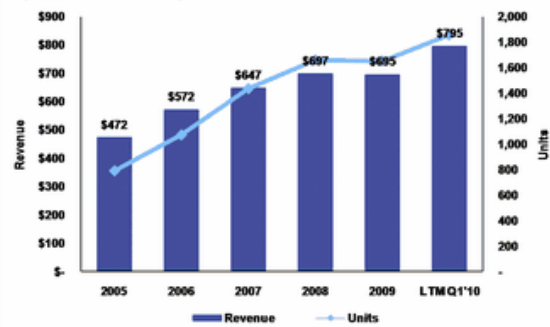
Chip Scale Packaging

Small form factor and greater I/O density

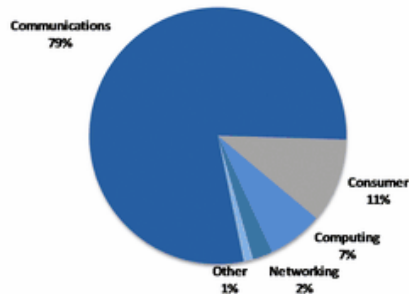


CSP Sales and Units – Annual Trends

(\$ and units in millions)



CSP Sales by End Markets



Based on Q1'10 net sales

CSP Sales and Units – Quarterly Trends

(\$ and units in millions)

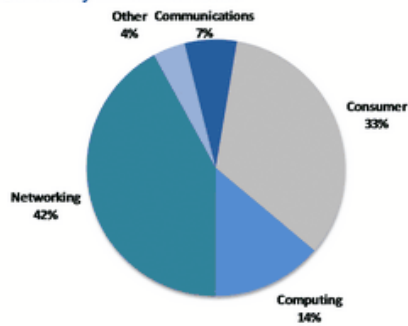


Ball Grid Array Packaging

Large body and high I/O supporting high performance applications



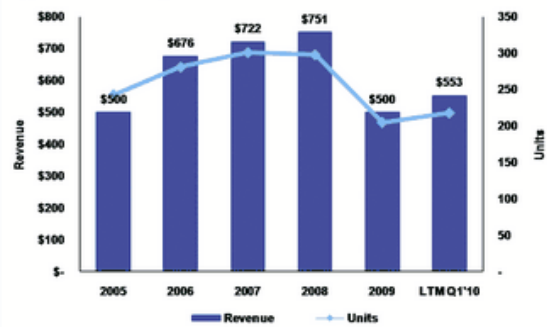
BGA Sales by End Markets



Based on Q1'10 net sales

BGA Sales and Units – Annual Trends

(\$ and units in millions)



BGA Sales and Units – Quarterly Trends

(\$ and units in millions)

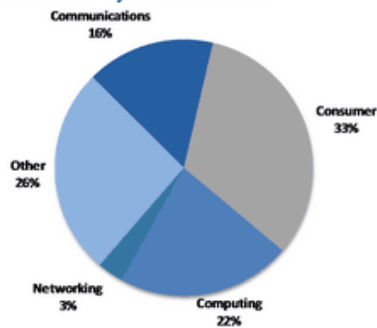


Leadframe Packaging

Favorable cost structure and supporting lower I/O applications



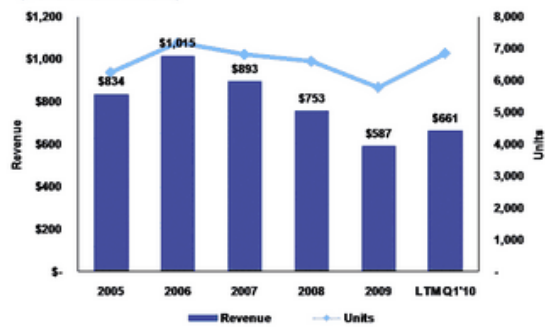
Leadframe Sales by End Markets



Based on Q1'10 net sales

Leadframe Sales and Units – Annual Trends

(\$ and units in millions)



Leadframe Sales and Units – Quarterly Trends

(\$ and units in millions)



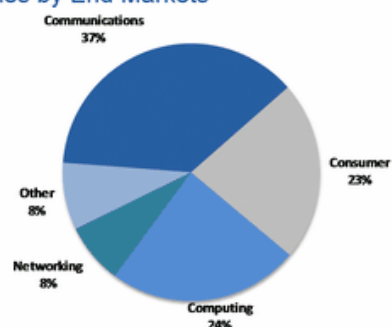


Test Sales and Units – Annual Trends

(\$ and units in millions)



Test Sales by End Markets



Based on Q1'10 net sales

Test Sales and Units – Quarterly Trends

(\$ and units in millions)



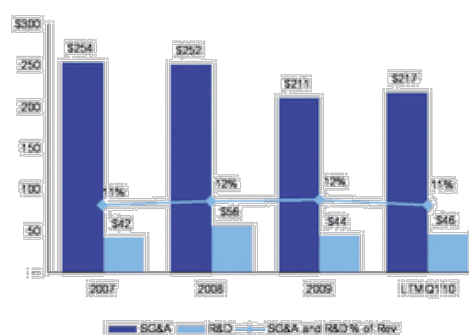
Maintaining and improving profitability in a cyclical industry through:

- capacity utilization and strategic capital investments,
- enhancing product mix using advanced technologies,
- sustaining a disciplined and competitive pricing strategy, and
- managing manufacturing costs and improving productivity

Revenue and Gross Profit
(\$ in millions)



Selling, General & Administrative and Research & Development
(\$ in millions)



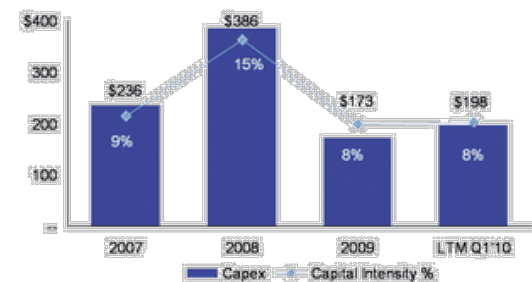
Free Cash Flow and Disciplined Capital Investment Focus



- Focused capital investment strategy
 - Advanced technologies including 3-D packaging, copper pillar and MEMS
 - Specific opportunities with key customers
 - Maintenance CapEx and cost reduction programs
- 2010 capital additions planned at about 14% of revenue

Capital Expenditures

Capital Intensity % defined as Purchases of Property, Plant and Equipment as a percentage of Net Sales (\$ in millions)



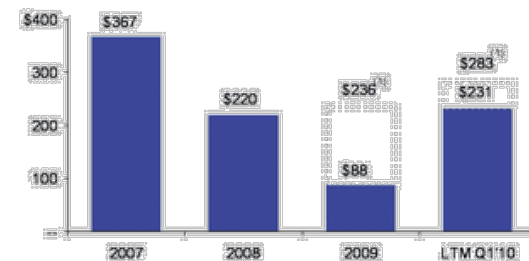
Operating Cash Flow

(\$ in millions)



Free Cash Flow⁽¹⁾

Free Cash Flow is defined as Operating Cash Flow less Purchases of Property, Plant and Equipment (\$ in millions)



(1) Excludes payments relating to Korean severance obligations and the resolution of a patent license dispute of which \$145 million was paid in 2009 and \$52 million was paid in LTM Q1'10

(2) Free Cash Flow is defined as Operating Cash Flow less Purchases of Property, Plant and Equipment. Refer to reconciliation of Non-GAAP measures in the appendix

Q1 2010 Overview



(in millions, except per share data)

	Q1'10	Q4'09	Q1'09
Revenue	\$ 646	\$ 668	\$ 389
Gross Profit	\$ 137	\$ 175	\$ 48
Gross Margin	21%	26%	12%
Net Income	\$ 44	\$ 88	\$ (22)
EPS (Basic)	\$ 0.24	\$ 0.48	\$ (0.12)
EPS (Diluted)	\$ 0.18	\$ 0.33	\$ (0.12)
Free Cash Flow ⁽¹⁾	\$ 37	\$ 44	\$ (106)
Utilization	84%	84%	45%

(1) Free Cash Flow is defined as Operating Cash Flow less Purchases of Property, Plant and Equipment. Refer to reconciliation of Non-GAAP measures in the appendix.

Consistent Focus on Deleveraging



Highlights

- Reduced total debt by \$336 million since 2007
- Reduced net debt by \$351 million since 2007
- Reduced annual interest expense by \$27 million since 2007

Total Debt and Cash Balance



Net Debt and Interest Expense

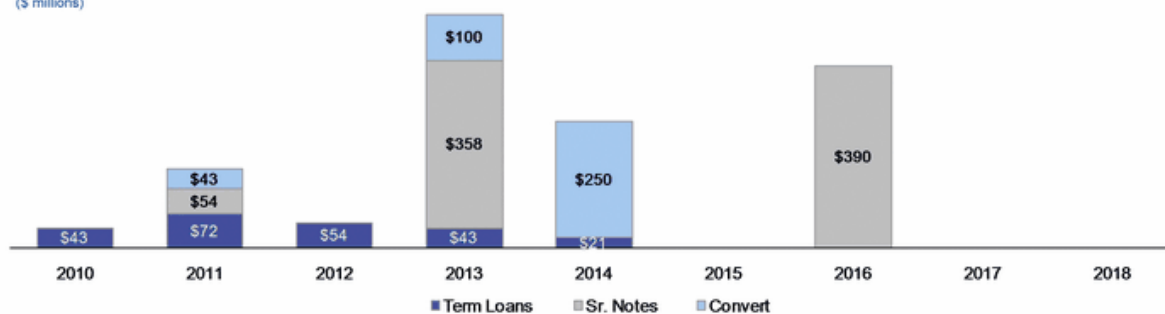


Pro Forma Maturities



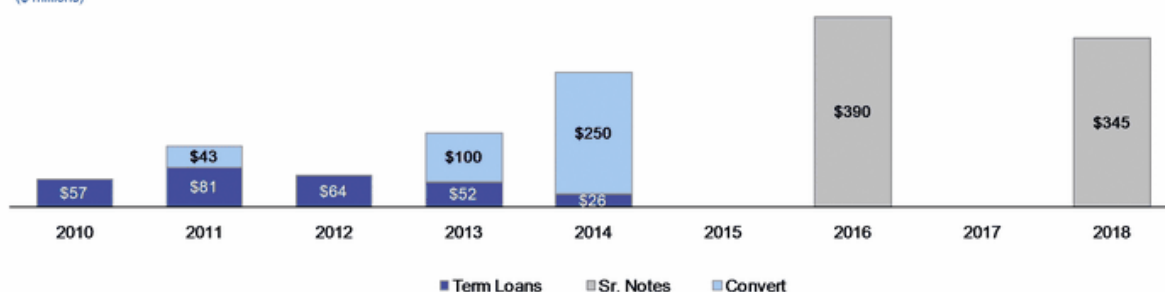
Maturity Profile as of March 31, 2010: \$1,428 million

(\$ millions)



Amkor's Pro Forma Maturity Profile as of March 31, 2010⁽¹⁾: \$1,408 million

(\$ millions)



(1) Includes the issuance of \$345m Senior Notes due 2018 of which the net proceeds and cash on hand will be used to redeem \$54m Senior Notes due 2011 and \$358m Senior Notes due 2013. Also includes \$47m Taiwan term loan

- Industry innovator and technology leader
- Partnering with our key customers
- Strong relationships with tier-1 semiconductor companies, foundries and OEMs
- Global manufacturing footprint
- Disciplined growth and focus on profitability
- Managing costs in line with customer demand
- Focusing on free cash flow and investment in technology
- Sound financial position and liquidity

Financial Reconciliation Table

	2007	2008	2009	LTM Q1'10	Q1 '10	Q4 '09	Q1 '09
Net Cash Provided by Operating Activities	\$603	\$606	\$262	\$429	\$104	\$106	(\$63)
Less: Purchases of Property, Plant and Equipment	(236)	(386)	(173)	(198)	(67)	(62)	(43)
Free Cash Flow ⁽¹⁾	\$367	\$220	\$88	\$231	\$37	\$44	(\$106)

(1) Free Cash Flow is defined as Operating Cash Flow less Purchases of Property, Plant and Equipment.

Free cash flow is not defined by generally accepted accounting principles. However, we believe free cash flow to be relevant and useful information to our investors because it provides them with additional information in assessing our liquidity, capital resources and financial operating results. Our management uses free cash flow in evaluating our liquidity, our ability to service debt and our ability to fund capital additions. However, this measure should be considered in addition to, and not as a substitute for, or superior to, cash flows or other measures of financial performance prepared in accordance with generally accepted accounting principles, and our definition of free cash flow may not be comparable to similarly titled measures reported by other companies.